

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...)	50202996	98		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B(...)	50203000	0		3	
		70	L2		
C-RAS-ML-0.10-070+070-460x305-TG150HF-...	50202542	100		4	A01
		70	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B(...)	50203001	183		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B(...)	50203001	0		6	
		70	L4		
C-RAS-ML-0.10-070+070-460x305-TG150HF-...	50202542	100		7	A02
		70	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B(...)	50203000	98		8	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...)	50202996	0		9	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	10	

Thickness after Pressing

B00: 890 µm Tol+: 100 µm Tol-: 100 µm Dmax: 990 µm Dmin: 790 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 1000 µm Tol+: 100 µm Tol-: 100 µm Dmax: 1100 µm Dmin: 900 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 895 µm

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